ABS1~ABS10

Rev.D May.-2017

DATA SHEET

"Yت / Descriptions

0.8A ´ ˛ ˚ Ł ד אַ ק ̃Ω ̧ ˥ ו ʕ ʒ ABS/LBF Ṃ Ł

0.8A Surface Mount Glass Passivated Bridge Rectifier ABS/LBF thin package.

◕ È / Features

אַ ד ק ל ̃ Ɑ ו ǂ ̧ כ ̧ ʒ ו ɾ ᵇ כ я χ433Y¢4333Y* ᵇ כ ̧ χ31;D ו گ ̃ ´ ˛ ˚ Ł ̀ ɦ β

Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V,Forward Current: 0.8A,High Surge Current Capability, Designed for Surface Mount Application. Halogen free product.

४ ڍ / Applications

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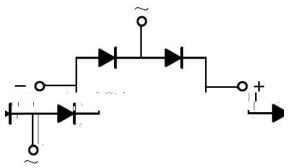
General purpose.

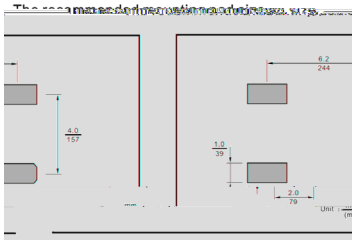
Л ڤ ̃ ̃ ̃ ع / Equivalent Circuit



ã ɹ ŭ ̃ / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



ɬ. ʜ ̀ / Marking

ŏ м ɿ ب ˝ See Marking Instructions.

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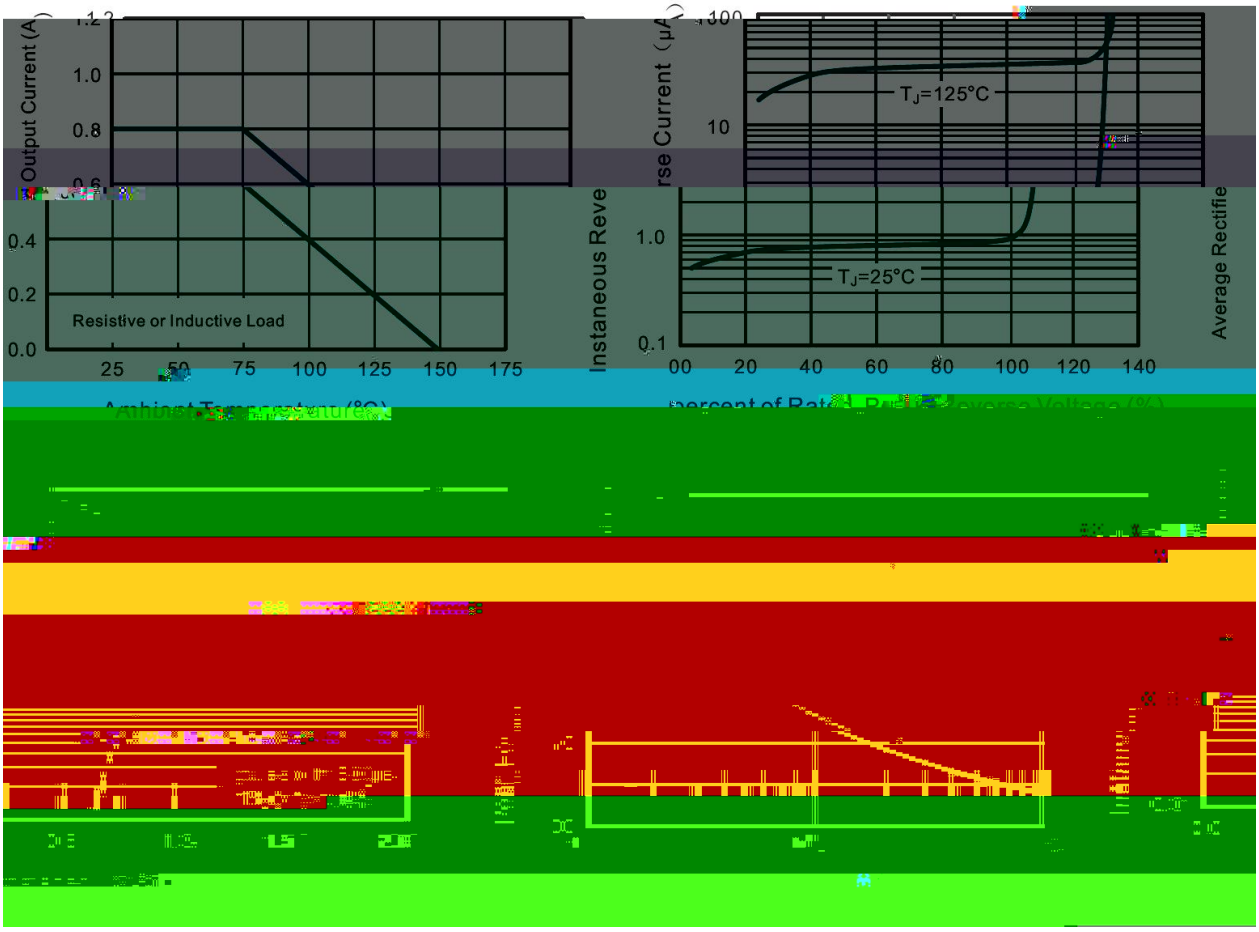
v ̈Ω Parameter	ϒ N Symbol	̈Ω Ө Rating						D Ђ Unit
		ABS1	ABS2	ABS4	ABS6	ABS8	ABS10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 40 C	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30						A
Typical Junction Capacitance Note1	C_i	13						pF
Typical Thermal Resistance Note2	$R_{\theta JA}$	85						/W
	$R_{\theta JL}$	30						/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~150						

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4 (5 5mm^2 copper pad.

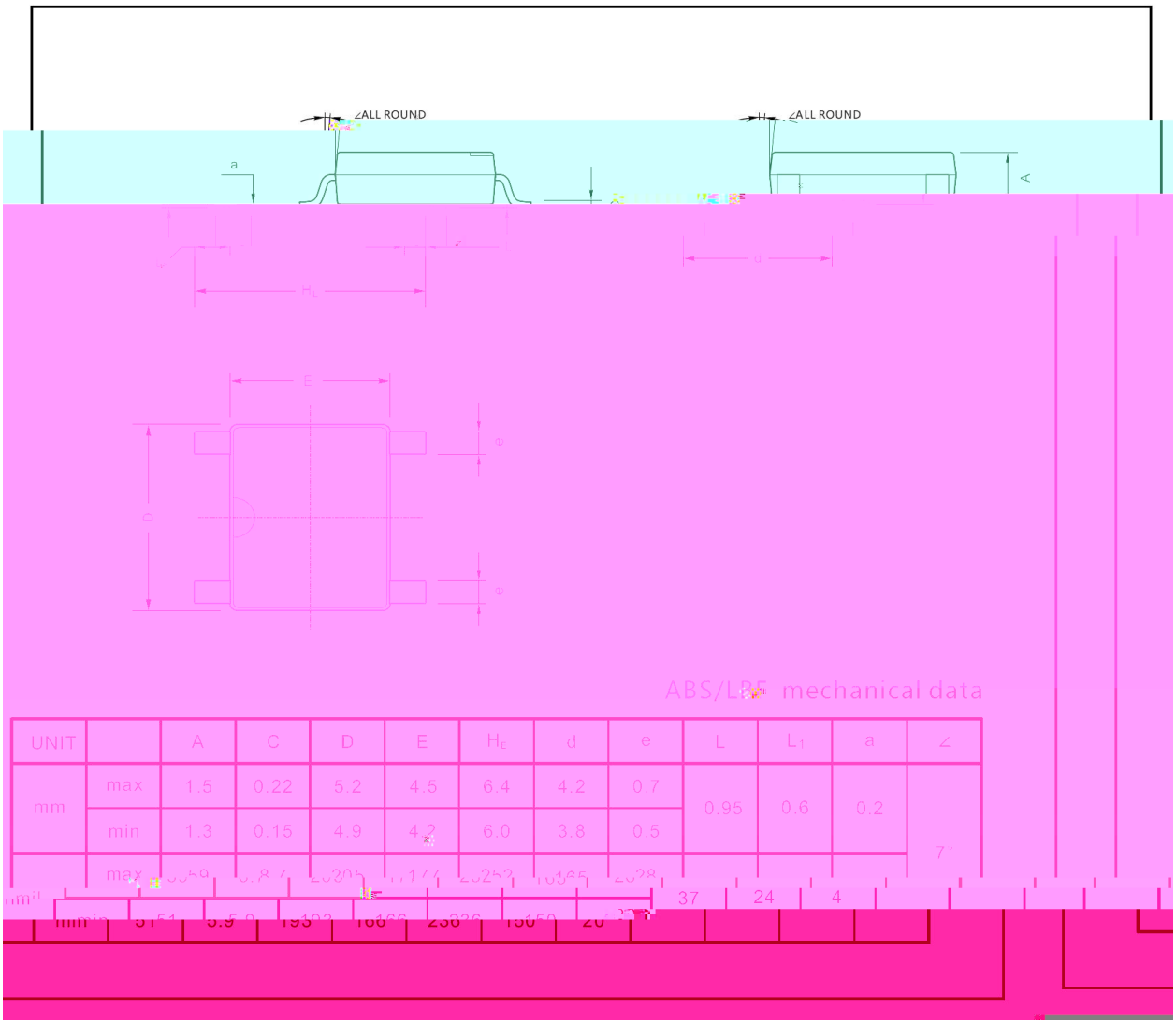
v ̈Ω Parameter	ϒ N Symbol	⅄ ⁝ ↾ ϒ Test Conditions	̈Ω Ө Rating	D Ђ Unit
Forward Voltage per element	V_F	I_F=0.4A	1.0	V
		I_F=0.8A	1.1	
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25	5.0	μA
		T_a=100	50	
		T_a=125	100	

ƒ ƒ Electrical Characteristic Curve



ᵘ Ė Ồ Ļ ƒ / Package Dimensions

ABS/LBF



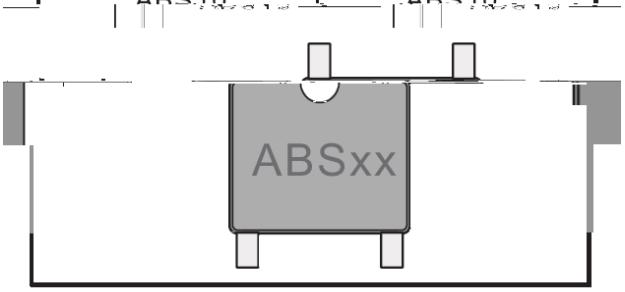
ABS/LBF mechanical data

UNIT		A	C	D	E	H_E	d	e	L	L_1	a	∠
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
	max											
mil									37	24	4	
	min											

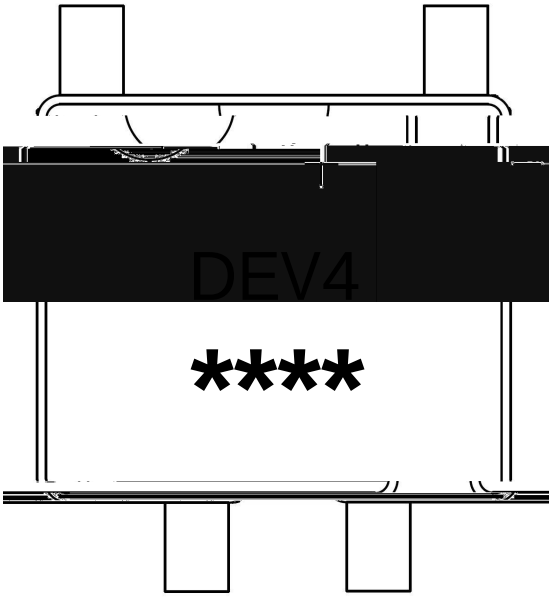
Ł. Ł Ω / Marking Instructions

Marking

Type number	Marking code
ABS1	ABS1
ABS2	ABS2
ABS4	ABS4
ABS6	ABS6
ABS8	ABS8
ABS10	ABS10



Ł. ĽŐ / Marking Instructions



ب ˝ χ

ABS1 χ ѭ ʒ ᴺ Ŋ

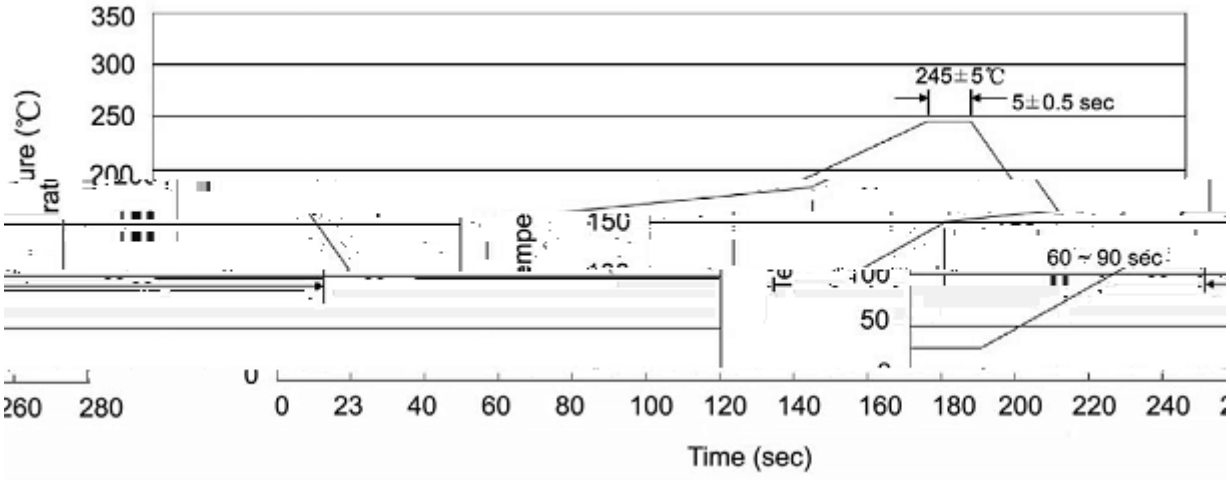
**** χ ѭ ɨ ɾ ŋ̋ ᴺ گ . ɪ ᴹ 1 Ѧ*ѭ ẉ ώ Ŋ ɪ ᵃ ˳ 3 Ѧ*ѭ Ẹ ώ ṇ ŋ̋ ᴺ Ŋ

Note:

ABS1 χ Product Type Code

**** χ Lot No. Code ɪ The 1st * means:YM Code ɪ The last 3 * means:little Lot No Code

ŧħ ʃ ╗ ẘ ´E ⅵ ʃ (ᾢ ʒ) / Wh p shudwxuh Su r il0h i ru LU Uhi0r z Vr0ghulq j+Se0luhh,



ب ˝ χ

1 ʃ ♬ □ ỷ 25 Ḱ 150 ɬ ı `H ʒ 60 Ḱ 90sec;

2 Š Ö □ ỷ 245 ° 5 ɬ ı `H ʒ ˋY ⅄ ⅉ 5 ° 0.5sec;

3 ì ˙ ⅂ ˛ ɔ ɯ ỷ ⅉ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:25~150 ɬ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

⅃ ʊ̀ ɋ ˝ `Y Ţ / Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɬ `H ʒ χ 10 ° 1 sec. Temp.:260±5